

# Bill of Materials

**TI DESIGNS**

TIPD114: Data Acquisition at 1KHz AC, 1mW, 18bit, 1Msps Reference Design

Item #	Quantity	Value	Designator	Description	Manufacturer	Part Number	Supplier Part Number 1
1	2		J4, J5	Connector, TH, SMA	Emerson Network Power	142-0701-201	
2	1		J3-B	Connector, Header, 10-Pos (10x2), Receptacle, 100x100-mil Pitch	Samtec, Inc.	SSW-105-22-F-D-VS-K	
3	2		J1-T, J2-T	Header, 100mil, 10x2, SMD	Samtec, Inc.	TSM-110-01-T-DV-P	
4	2		J1-B, J2-B	Connector, Receptacle, 100mil, 10x2, Gold plated, SMD	Samtec, Inc.	SSW-110-22-F-D-VS-K	
5	1		J3-T	Header, 100mil, 5x2, SMD	Samtec, Inc.	TSM-105-01-T-DV-P	
6	2		C17, C19	CAP, CERM, 10uF, 16V, +/-10%, X7R, 1206	MuRata	GRM31CR71C106KAC7L	
7	2		JP1, JP2	Header, TH, 100mil, 1x3, Gold plated, 230 mil above insulator	Sullins Connector Solutions	PBC03SAAN	
8	3		C16, C18, C20	CAP, CERM, 1000pF, 50V, +/-5%, C0G/NP0, 0603	Kemet	C0603C102J5GAC	
9	1		TP1	Test Point, Miniature, Red, TH	Keystone	5000	
10	2		C9, C10	CAP, 10000pF, 0603, 5%, 50V, C0G	TDK	C1608C0G1H103J080AA	
11	5		C4, C7, C8, C13, C21	CAP, CERM, 1uF, 10V, +/-10%, X7R, 0603	MuRata	GRM188R71A105KA61D	
12	1		C3	CAP, CERM, 4700pF, 25V, +/-5%, C0G/NP0, 0603	TDK	C1608C0G1E472J	
13	3		SH-JP1, SH-JP2, SH-JP3	Shunt, 100mil, Gold plated, Black	3M	969102-0000-DA	
14	1		R22	RES, 10.0 ohm, 1%, 0.1W, 0603	Vishay-Dale	CRCW060310R0FKEA	
15	1		R3	RES, 4.75 ohm, 1%, 0.1W, 0603	Vishay-Dale	CRCW06034R75FKEA	
16	3		R4, R9, R10	RES, 1.00k ohm, 1%, 0.1W, 0603	Vishay-Dale	CRCW06031K00FKEA	
17	5		R5, R6, R12, R27, R31	RES, 10.0k ohm, 1%, 0.1W, 0603	Vishay-Dale	CRCW060310K0FKEA	
18	2		C2, C5	CAP, CERM, 0.1uF, 25V, +/-10%, X7R, 0603	AVX	06033C104KAT2A	
19	3		R23, R25, R30	RES, 0 ohm, 5%, 0.1W, 0603	Panasonic	ERJ-3GEY0R00V	
20	7		R1, R2, R28, R29, R32, R33, R35	RES, 47.0 ohm, 1%, 0.1W, 0603	Yageo America	RC0603FR-0747RL	
21	1		U7		Microchip	24LC256-I/ST	
22	1		U1	ADC 1MSPS 18bit Fully-Diff MSOP-10	Texas Instruments	ADS8881IDGS	
23	1		C6	CAP, CERM, 22uF, 16V, +/-10%, X5R, 1206	MuRata	GRM31CR61C226KE15L	
24	1		JP3	Header, 100mil, 2x1, Gold plated, TH	TE Connectivity	5-146261-1	
25	1		U6	OpAmp, 1.8V, Low Power, Low Drift	Texas Instruments	OPA2333AIDGKR	
26	1		U2	OpAmp, Low Power, Low Noise, RRIO, 1MHz, 1.8V	Texas Instruments	OPA313IDBVR	
27	1		U3	Ref, Voltage, 2.5V, 3.9uA, SC70-3	Texas Instruments	REF3325AIDBZT	
28	15		C1, C11, C12, C14, C23, C24,	Uninstalled		N/A	

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